

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph under the heading "Cross-Reference To Related Applications" added by the Preliminary Amendment filed with this divisional application on March 1, 2004, with the following amended paragraph:

This application is a division of ~~co-pending~~ U.S. Application No. 10/019,508, filed on December 21, 2001, now abandoned, and entitled, "Side-Emission type Semiconductor Light-Emitting Device and Manufacturing Method Thereof", the disclosure of which is incorporated herein by reference.

AMENDMENTS TO THE CLAIMS:

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Currently Amended) A side-emission type semiconductor light-emitting device, comprising:
 - a substrate formed with an electrode;
 - an LED chip bonded onto said substrate;
 - a transparent or translucent resin with which said LED chip is molded; and
 - a reflector which reflects a light emitted from said LED chip, wherein said transparent or translucent resin has a convex portion, and said reflector has a throughhole ~~concave portion~~ to be fitted into said convex portion.
5. (Currently Amended) A side-emission type semiconductor light-emitting device ~~according to claim 4~~, comprising:
 - a substrate formed with an electrode;

an LED chip bonded onto said substrate;
a transparent or translucent resin with which said LED chip is molded; and
a reflector which reflects a light emitted from said LED chip, wherein
said transparent or translucent resin has a convex portion, and said reflector has a
concave portion to be fitted into said convex portion, and wherein
said concave portion is a throughhole having a diameter which becomes larger from
one main surface to other main surface of said reflector.

6. (Original) A side-emission type semiconductor light-emitting device
according to claim 5, wherein said one main surface is a surface brought into contact with
said transparent or translucent resin, and said other main surface is a surface exposed to
outside.

7. (Currently Amended) A side-emission type semiconductor light-emitting device
according to claim 4, wherein said LED chip has a bonding wire extending from a top
surface, and said throughhole concave portion is formed directly above said LED chip.

8. (Cancelled)

9. (Cancelled)

10. (Cancelled)

11. (Cancelled)

12. (Cancelled)

13. (Cancelled)

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14. (Previously Added) A side-emission type semiconductor light-emitting device according to claim 5, wherein said LED chip has a bonding wire extending from a top surface, and said concave portion is formed directly above said LED chip.

15. (Previously Added) A side-emission type semiconductor light-emitting device according to claim 6, wherein said LED chip has a bonding wire extending from a top surface, and said concave portion is formed directly above said LED chip.